

ABSTRACT

Title of the Invention: PHOTSENSITIVE RESIN COMPOSITION, PHOTSENSITIVE RESIN COMPOSITION FILM, CURED PRODUCT, AND ELECTRONIC COMPONENT USING SAME

Provided is a photosensitive resin composition having excellent patterning property and providing excellent pressure resistance (elastic modulus) of a cured product. This photosensitive resin composition contains (A) a polyimide, (B) a cationic polymerizable compound, (C) a photocationic polymerization initiator, and (D) crystalline silica and has negative photosensitivity.

[No Figure]